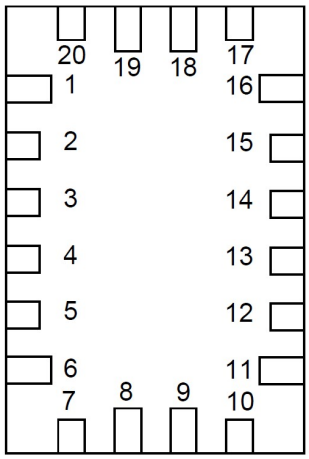
General Description

Renesas SLG7RN46708 is a low power and small form device. The SoC is housed in a 2mm x 3mm STQFN package which is optimal for using with small devices.

Features

- Low Power Consumption
- Pb - Free / RoHS Compliant
- Halogen - Free
- STQFN - 20 Package

Pin Configuration

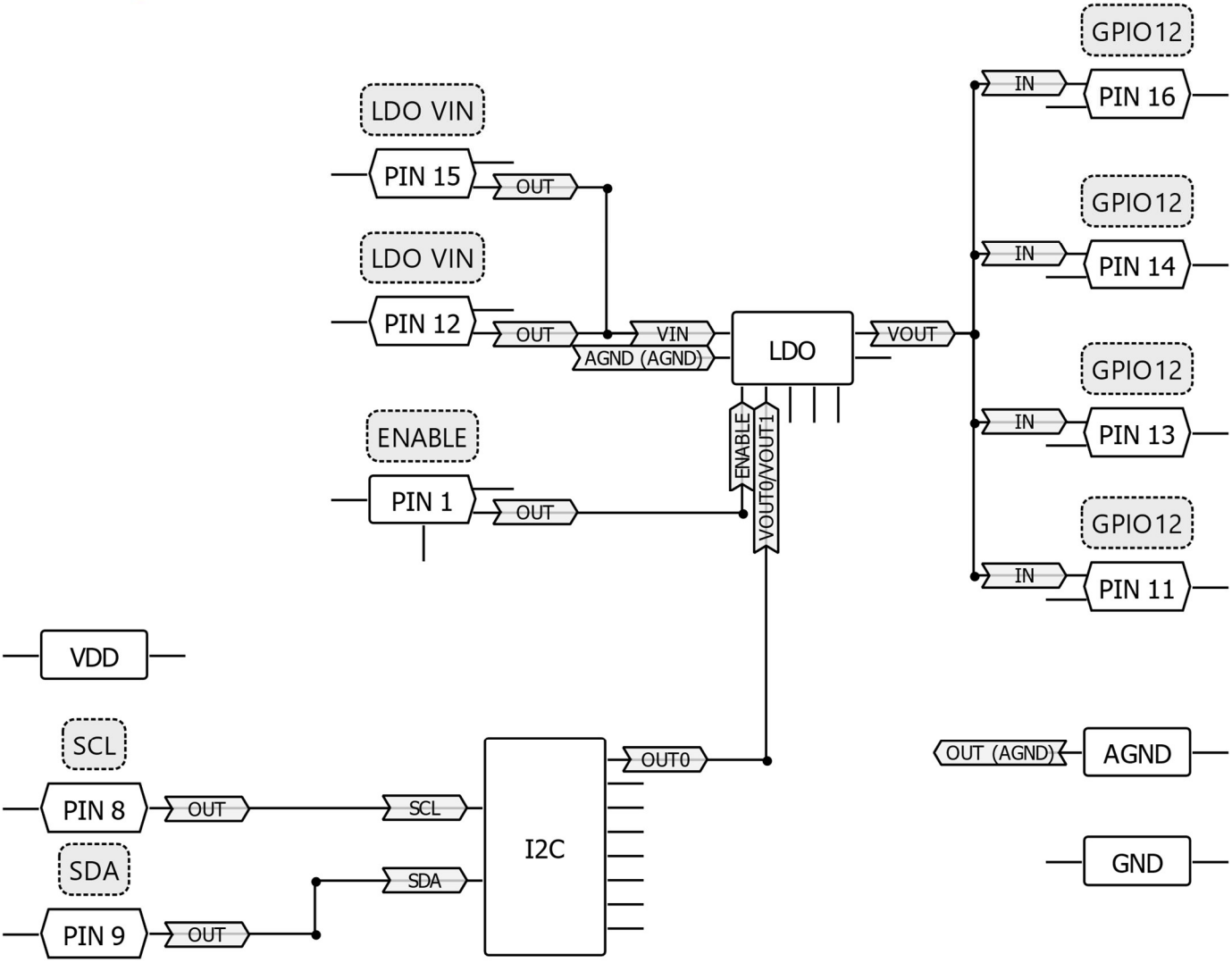


STQFN-20
(Top view)

Pin name

Pin #	Pin name	Pin #	Pin name
1	ENABLE	11	GPIO12
2	NC	12	LDO VIN
3	NC	13	GPIO12
4	NC	14	GPIO12
5	NC	15	LDO VIN
6	NC	16	GPIO12
7	VDD	17	AGND
8	SCL	18	NC
9	SDA	19	NC
10	NC	20	GND

Block Diagram



Pin Configuration

Pin #	Pin Name	Type	Pin Description	Internal Resistor
1	ENABLE	Digital Input	Digital Input without Schmitt trigger	100kΩ pulldown
2	NC	--	Keep Floating or Connect to GND	--
3	NC	--	Keep Floating or Connect to GND	--
4	NC	--	Keep Floating or Connect to GND	--
5	NC	--	Keep Floating or Connect to GND	--
6	NC	--	Keep Floating or Connect to GND	--
7	VDD	PWR	Supply Voltage	--
8	SCL	Digital Input	Digital Input without Schmitt trigger	floating
9	SDA	Digital Input	Digital Input without Schmitt trigger	floating
10	NC	--	Keep Floating or Connect to GND	--
11	GPIO12	Analog Output	LDO VOUT Analog Output	floating
12	LDO VIN	Analog Input	LDO VIN Analog Input	floating
13	GPIO12	Analog Output	LDO VOUT Analog Output	floating
14	GPIO12	Analog Output	LDO VOUT Analog Output	floating
15	LDO VIN	Analog Input	LDO VIN Analog Input	floating
16	GPIO12	Analog Output	LDO VOUT Analog Output	floating
17	AGND	AGND	Ground	--
18	NC	--	Keep Floating or Connect to GND	--
19	NC	--	Keep Floating or Connect to GND	--
20	GND	GND	Ground	--

Ordering Information

Part Number	Package Type
SLG7RN46708V	20-pin STQFN - Tape and Reel (3k units)

Absolute Maximum Conditions

Parameter	Min.	Max.	Unit
Supply Voltage on VDD relative to GND	-0.3	7	V
DC Input Voltage	GND - 0.5V	VDD + 0.5V	V
Current at Input Pin	-1.0	1.0	mA
Input leakage (Absolute Value)	--	1000	nA
Storage Temperature Range	-65	150	°C
Junction Temperature	--	150	°C
ESD Protection (Human Body Model)	2000	--	V
ESD Protection (Charged Device Model)	1300	--	V
Moisture Sensitivity Level	1		

Electrical Characteristics

Symbol	Parameter	Condition/Note	Min.	Typ.	Max.	Unit
V_{DD}	Supply Voltage		2.3	3.3	5.5	V
T_A	Operating Temperature		-40	25	85	°C
C_{VDD}	Capacitor Value at VDD		--	0.1	--	µF
C_{IN}	Input Capacitance		--	4	--	pF
I_Q	Quiescent Current	Static inputs and floating outputs. PINs 8,9 are HIGH	--	1	--	µA
V_O	Maximal Voltage Applied to any PIN in High-Impedance State		--	--	VDD+0.3	V
I_{VDD}	Maximum Average or DC Current Through VDD Pin (Per chip side, see Note 2)	T_J = 85°C	--	--	73	mA
		T_J = 110°C	--	--	35	mA
I_{GND}	Maximum Average or DC Current Through GND Pin (Per chip side, see Note 2)	T_J = 85°C	--	--	152	mA
		T_J = 110°C	--	--	72	mA
V_{IH}	HIGH-Level Input Voltage	Logic Input	0.7xVDD	--	VDD+0.3	V
V_{IL}	LOW-Level Input Voltage	Logic Input	GND-0.3	--	0.3xVDD	V
R_{PULL_DOWN}	Internal Pull Down Resistance	Pull down on PIN 1	--	100	--	kΩ
T_{SU}	Startup Time	From VDD rising past PON_{THR}	--	1.3	--	ms
PON_{THR}	Power On Threshold	V_{DD} Level Required to Start Up the Chip	1.34	1.55	1.74	V
$POFF_{THR}$	Power Off Threshold	V_{DD} Level Required to Switch Off the Chip	1.05	1.25	1.45	V

Note:
1. DC or average current through any pin should not exceed value given in Absolute Maximum Conditions.
2. The GreenPAK's power rails are divided in two sides. PINs 1, 2, 3, 4, 5 and 6 are connected to one side, PINs 8, 9, 10, 18 and 19 to another.
3. Guaranteed by Design.

I²C Specifications

Symbol	Parameter	Condition/Note	Min.	Typ.	Max.	Unit
F_{SCL}	Clock Frequency, SCL	V_{DD} = (2.3...5.5) V	--	--	400	kHz
t_{LOW}	Clock Pulse Width Low	V_{DD} = (2.3...5.5) V	1300	--	--	ns
t_{HIGH}	Clock Pulse Width High	V_{DD} = (2.3...5.5) V	600	--	--	ns
t_I	Input Filter Spike Suppression (SCL, SDA)	V_{DD} = 2.5V ± 8%	--	--	168	ns
		V_{DD} = 3.3V ± 10%	--	--	157	ns
		V_{DD} = 5.0V ± 10%	--	--	156	ns
t_{AA}	Clock Low to Data Out Valid	V_{DD} = (2.3...5.5) V	--	--	900	ns
t_{BUF}	Bus Free Time between Stop and Start	V_{DD} = (2.3...5.5) V	1300	--	--	ns
t_{HD_STA}	Start Hold Time	V_{DD} = (2.3...5.5) V	600	--	--	ns
t_{SU_STA}	Start Set-up Time	V_{DD} = (2.3...5.5) V	600	--	--	ns
t_{HD_DAT}	Data Hold Time	V_{DD} = (2.3...5.5) V	0	--	--	ns
t_{SU_DAT}	Data Set-up Time	V_{DD} = (2.3...5.5) V	100	--	--	ns
t_R	Inputs Rise Time	V_{DD} = (2.3...5.5) V	--	--	300	ns
t_F	Inputs Fall Time	V_{DD} = (2.3...5.5) V	--	--	300	ns
t_{SU_STO}	Stop Set-up Time	V_{DD} = (2.3...5.5) V	600	--	--	ns
t_{DH}	Data Out Hold Time	V_{DD} = (2.3...5.5) V	50	--	--	ns

Chip address

HEX	BIN	DEC
0x70	1110000	112

I2C Description

1. I2C Basic Command Structure

Each command to the I2C Serial Communications block begins with a Control Byte. The bits inside this Control Byte are shown in Figure 1. After the Start bit, the first four bits are a control code, which can be set by the user in reg<1867:1864>. The Block Address is the next three bits (A10, A9, A8), which will define the most significant bits in the addressing of the data to be read (“1”) or written (“0”) by the command. This Control Byte will be followed by an Acknowledge bit (ACK).

With the exception of the Current Address Read command, all commands will have the Control Byte followed by the Word Address. The Word Address, in conjunction with the three address bits in the Control Byte, will define the specific data byte to be read or written in the command. Figure 1 shows this basic command structure.

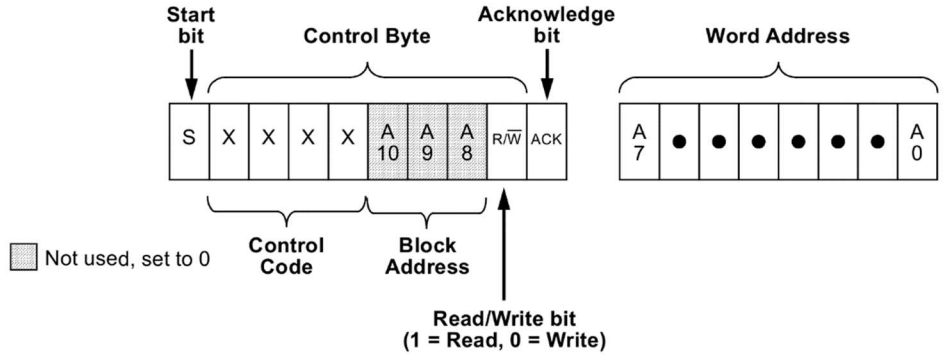


Figure1. I2C Basic Command Structure

2. I2C Serial General Timing

Shown in Figure 2 is the general timing characteristics for the I2C Serial Communications block.

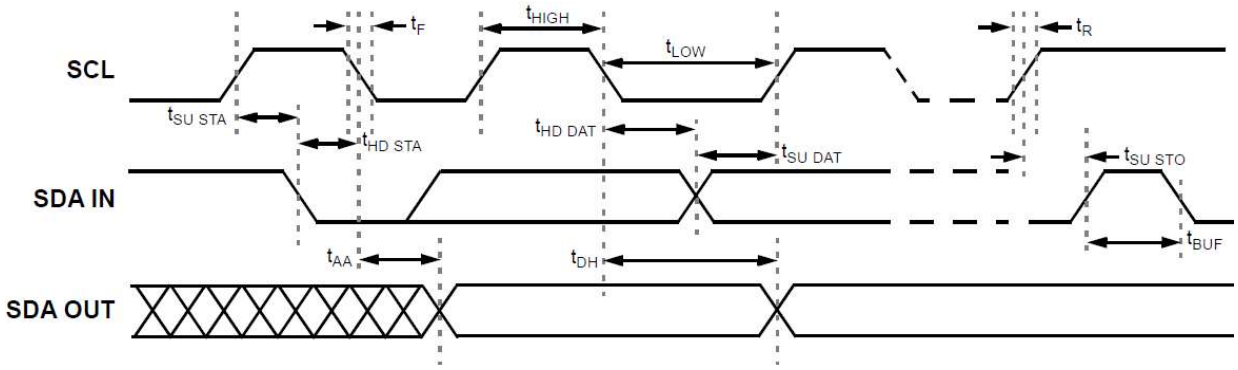


Figure2. I2C Serial General Timing

3. I2C Serial Communications: Read and Write Commands

Following the Start condition from the master, the Control Code [4 bits], the block address [3 bits] and the R/W bit (set to “0”), is placed onto the bus by the Bus Master. After the I2C Serial Communications block has provided an Acknowledge bit (ACK) the next byte transmitted by the master is the Word Address. The Block Address is the next three bits, and is the higher order addressing bits (A10, A9, A8), which when added to the Word Address will together set the internal address pointer in the SLG7RN46708 to the correct data byte to be written. After the SLG7RN46708 sends another Acknowledge bit, the Bus Master will transmit the data byte to be written into the addressed memory location. The SLG7RN46708 again provides an Acknowledge bit and then the Bus Master generates a Stop condition. The internal write cycle for the data will take place at the time that the SLG7RN46708 generates the Acknowledge bit.

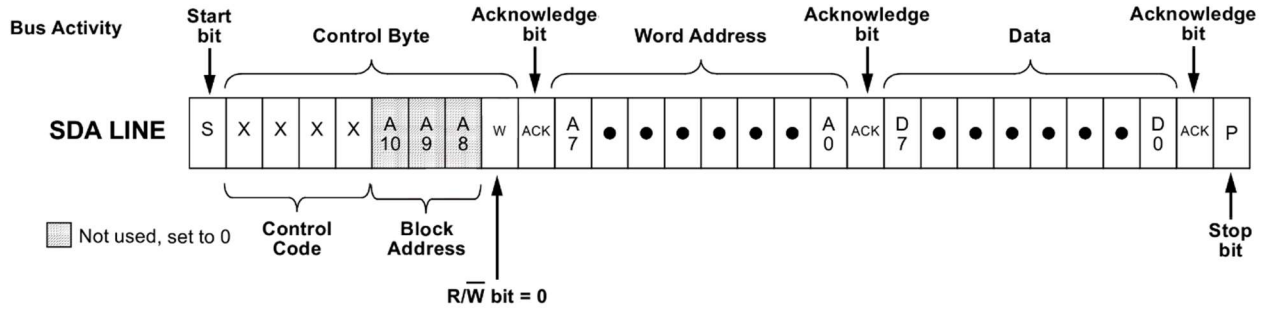


Figure3. I2C Write Command

The Random Read command starts with a Control Byte (with R/$\overline{W}$ bit set to “0”, indicating a write command) and Word Address to set the internal byte address, followed by a Start bit, and then the Control Byte for the read (exactly the same as the Byte Write command). The Start bit in the middle of the command will halt the decoding of a Write command, but will set the internal address counter in preparation for the second half of the command. After the Start bit, the Bus Master issues a second control byte with the R/$\overline{W}$ bit set to “1”, after which the SLG7RN46708 issues an Acknowledge bit, followed by the requested eight data bits.

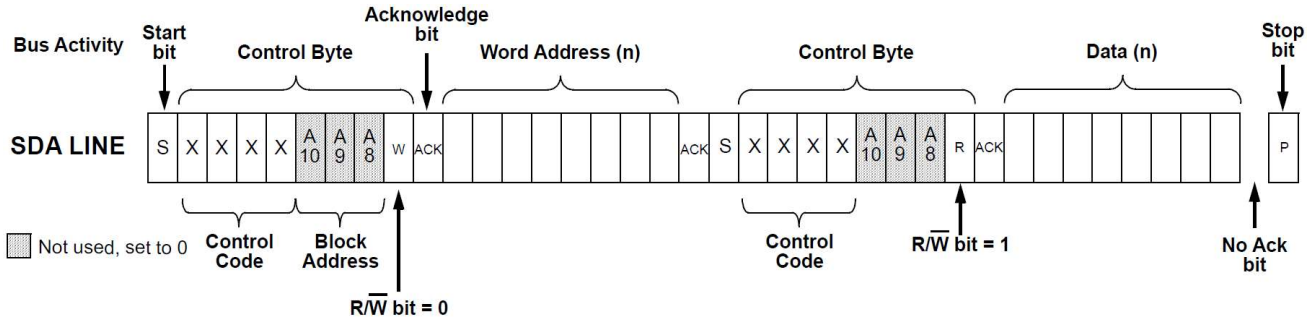


Figure4. I2C Random Read Command

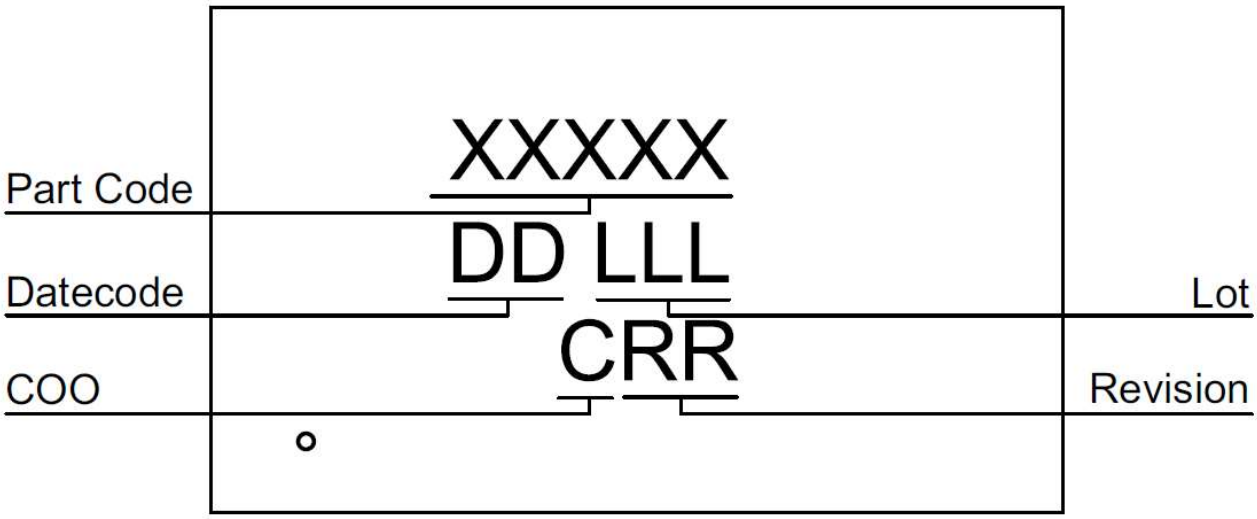
4. I2C register control data

Address Byte	Register Bit	Block	Function
0xF4	reg<1952>	Virtual Input <0>	LDO mode VOUT0 (0) or VOUT1 (1). Default is 0.
	reg<1959:1953>	--	Do not used

5. I2C Commands:

1. [start] [0x70] [w] [0xF4] [xxxxxxx(OUT0)] [stop] // set LDO mode to VOUT0 (OUT0 = 0) or VOUT1 (OUT0 = 1)
2. [start] [0x70] [w] [0xF4] [start] [0x70] [R] [xxxxxxx(OUT0)][stop] // read current LDO mode

Package Top Marking



XXXXX – Part ID Field: identifies the specific device configuration
DD – Date Code Field: Coded date of manufacture
LLL – Lot Code: Designates Lot #
C – Assembly Site/COO: Specifies Assembly Site/Country of Origin
RR – Revision Code: Device Revision

Datasheet Revision	Programming Code Number	Lock Status	Checksum	Part Code	Revision	Date
0.10	001	U	0xCB4881D2			07/10/2023

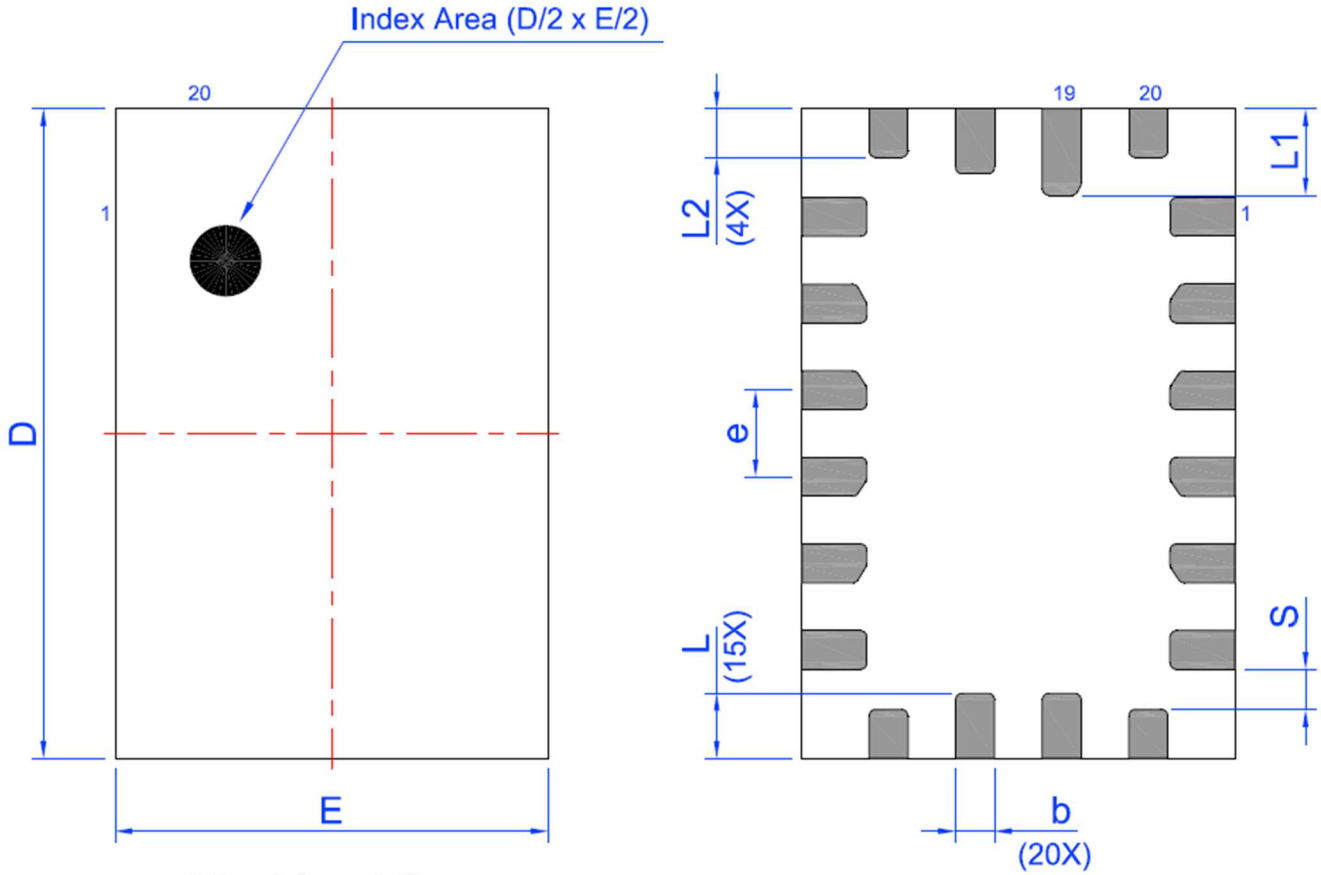
Lock coverage for this part is indicated by √, from one of the following options:

√	Unlocked
	Locked for read, bits <1535:0>
	Locked for write, bits <1535:0>
	Locked for write all bits
	Locked for read and write bits <1535:0>
	Locked for read bits <1535:0> and write of all bits

The IC security bit is locked/set for code security for production unless otherwise specified. The Programming Code Number is not changed based on the choice of locked vs. unlocked status.

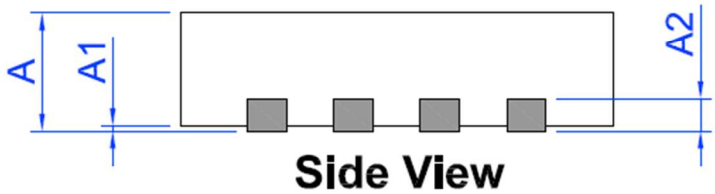
Package Drawing and Dimensions

STQFN 20L 2x3mm 0.4P FCD Package
JEDEC MO-220, Variation WECE



Marking View

BTM View



Side View

Unit: mm

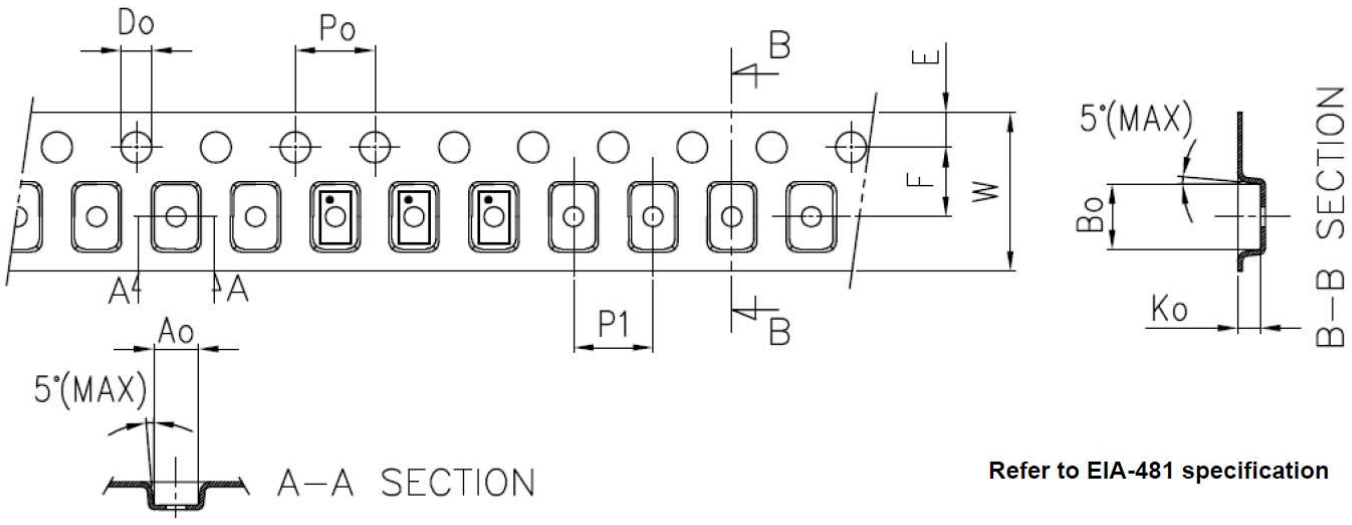
Symbol	Min	Nom.	Max	Symbol	Min	Nom.	Max
A	0.50	0.55	0.60	D	2.95	3.00	3.05
A1	0.005	-	0.050	E	1.95	2.00	2.05
A2	0.10	0.15	0.20	L	0.25	0.30	0.35
b	0.13	0.18	0.23	L1	0.35	0.40	0.45
e	0.40 BSC			L2	0.175	0.225	0.275
S	0.185 TYP						

Tape and Reel Specification

Package Type	# of Pins	Nominal Package Size [mm]	Max Units		Reel & Hub Size [mm]	Leader (min)		Trailer (min)		Tape Width [mm]	Part Pitch [mm]
			per Reel	per Box		Pockets	Length [mm]	Pockets	Length [mm]		
STQFN 20L 2x3mm 0.4P FCD	20	2 x 3 x 0.55	3000	3000	178/60	100	400	100	400	8	4

Carrier Tape Drawing and Dimensions

Package Type	Pocket BTM Length	Pocket BTM Width	Pocket Depth	Index Hole Pitch	Pocket Pitch	Index Hole Diameter	Index Hole to Tape Edge	Index Hole to Pocket Center	Tape Width
	A0	B0	K0	P0	P1	D0	E	F	W
STQFN 20L 2x3mm 0.4P FCD	2.2	3.15	0.76	4	4	1.5	1.75	3.5	8



Refer to EIA-481 specification

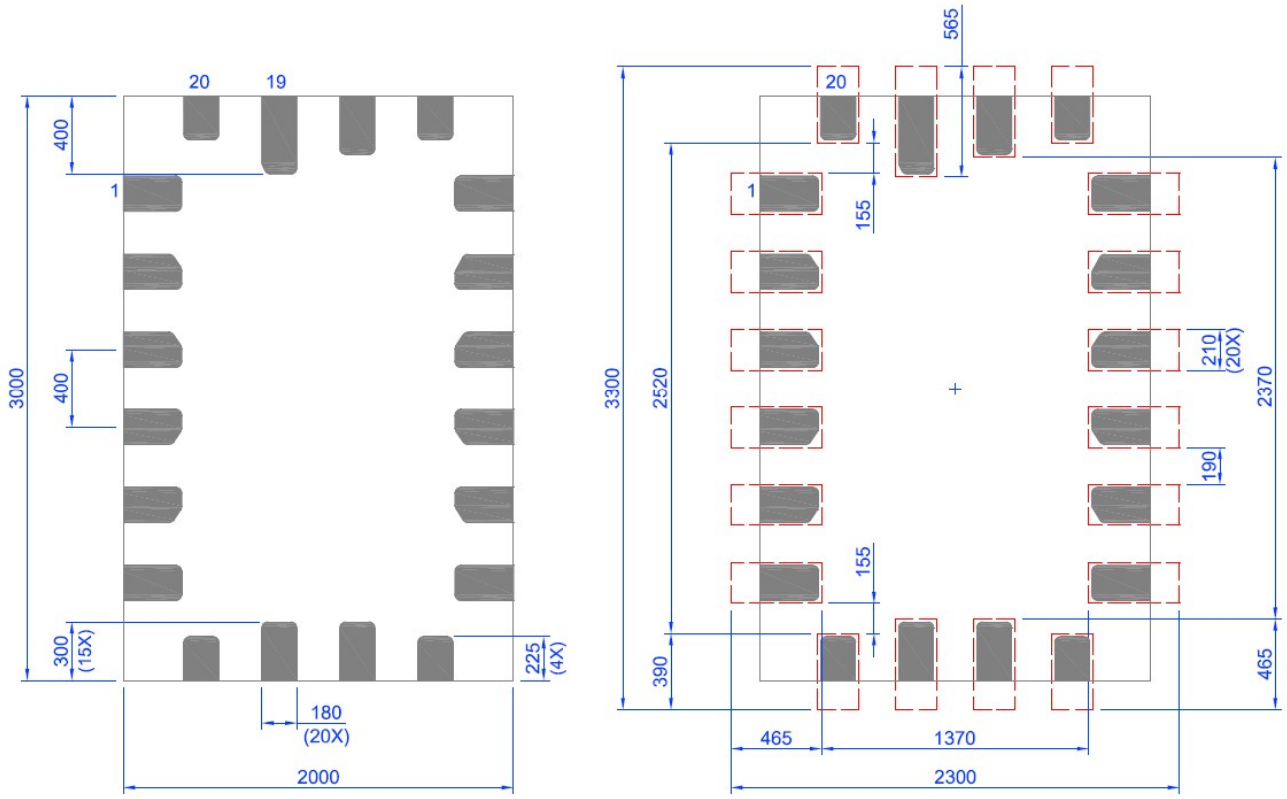
Recommended Reflow Soldering Profile

Please see IPC/JEDEC J-STD-020: latest revision for reflow profile based on package volume of 3.30 mm^3 (nominal). More information can be found at www.jedec.org.

Recommended Land Pattern

Exposed Pad
(PKG face down)

Recommended Land Pattern
(PKG face down)



Unit:um

Datasheet Revision History

Date	Version	Change
07/10/2023	0.10	New design

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